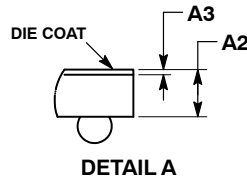
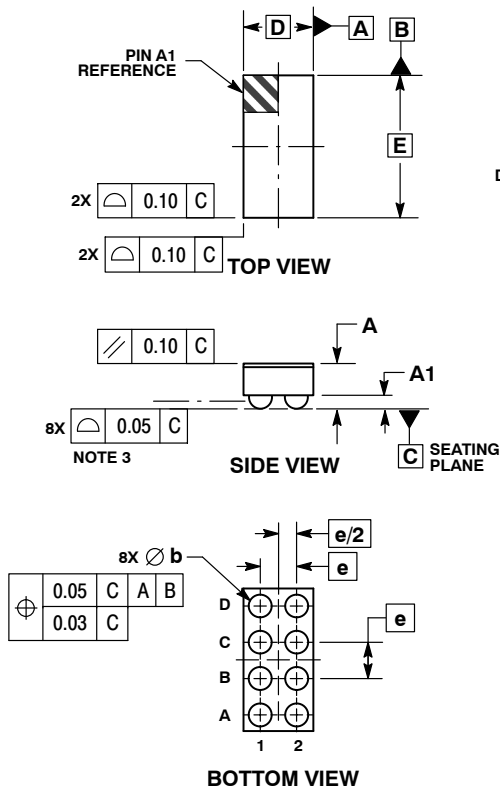




SCALE 4:1

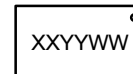
WLCSP8, 1.57x0.77
CASE 499BQ
ISSUE A

DATE 01 SEP 2015



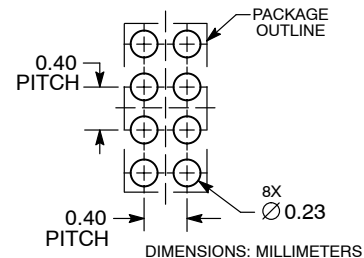
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.50
A1	0.13	0.17
A2	0.30 REF	
A3	0.025 BSC	
b	0.21	0.25
D	0.77 BSC	
E	1.57 BSC	
e	0.40 BSC	

GENERIC MARKING DIAGRAM*


XX = Specific Device Code
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*


*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP8, 1.57X0.77	PAGE 1 OF 1

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